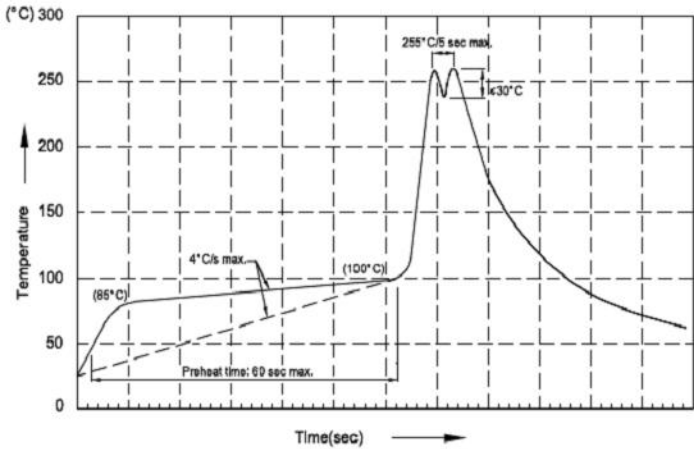
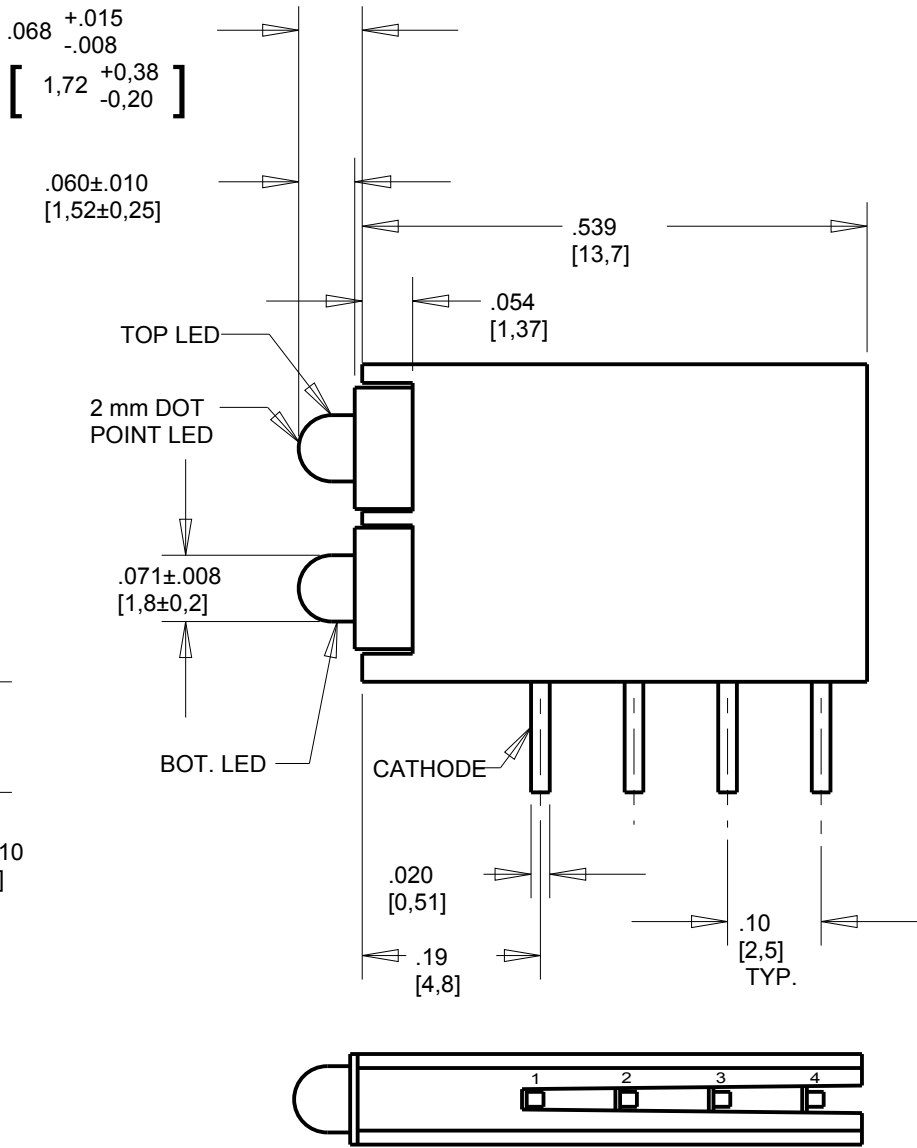
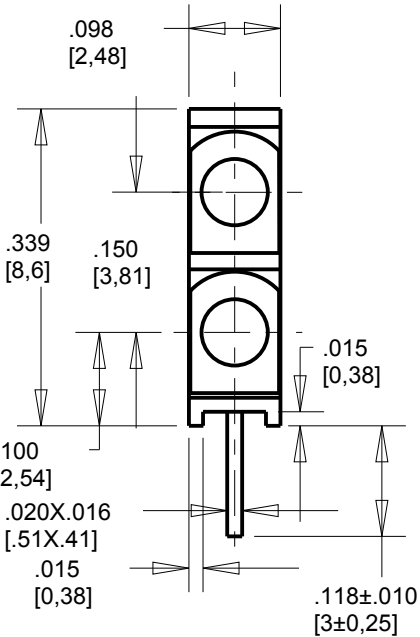
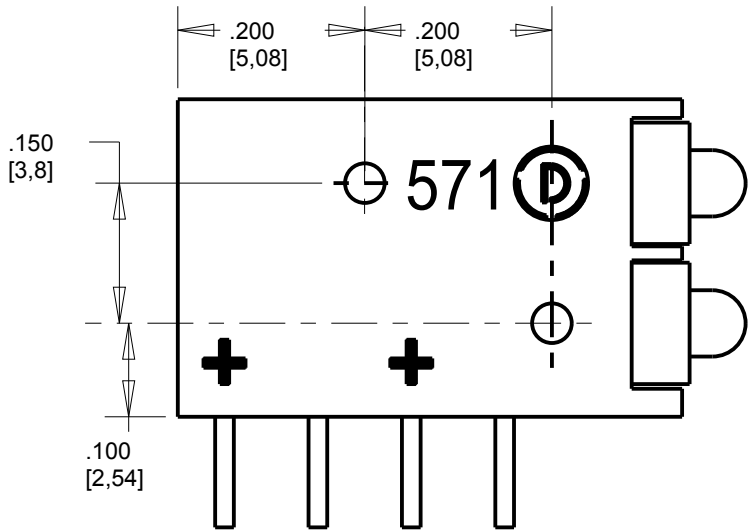


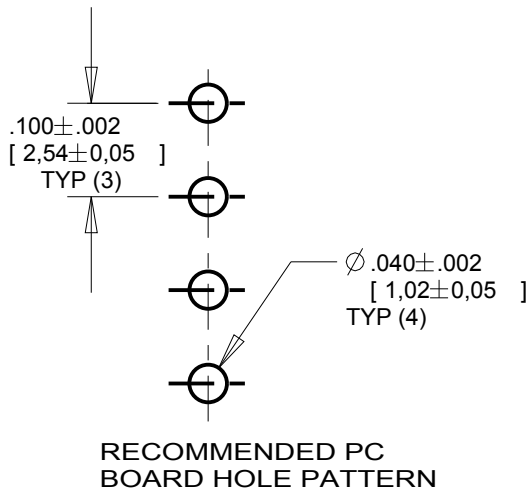
ASSY. NO.	LED COLOR (DIFFUSED)	
	TOP POSITION	BOTTOM POSITION
571-0101F	BLANK	RED
571-0102F	BLANK	GREEN
571-0103F	BLANK	YELLOW
571-0110F	RED	BLANK
571-0111F	RED	RED
571-0112F	RED	GREEN
571-0113F	RED	YELLOW
571-0120F	GREEN	BLANK
571-0121F	GREEN	RED
571-0122F	GREEN	GREEN
571-0123F	GREEN	YELLOW
571-0130F	YELLOW	BLANK
571-0131F	YELLOW	RED
571-0132F	YELLOW	GREEN
571-0133F	YELLOW	YELLOW

RoHS Compliant 571-01XXF
Part Numbers with the "F" suffix ending are RoHS Compliant.
Example: 571-0112F
Packaging is marked with "RoHS Compliant" label or equivalent markings.
Parts can be wave soldered, dip soldered or hand soldered using typical lead-free soldering process with max 255°C temp. for 5 sec.



RECOMMENDED WAVE SOLDERING PROFILE

OPERATING CHARACTERISTICS AT 25° C AMBIENT						
CHARACTERISTICS	COLOR	MIN	TYP	MAX	UNITS	TEST CONDITIONS
LUMINOUS INTENSITY	RED	8	15		mcd	I _F = 10 mA
	YELLOW	5	8			
	GREEN	6	20			
FORWARD VOLTAGE	RED		2.0	2.5	V	I _F = 20 mA
	YELLOW		1.95	2.5		
	GREEN		2.0	2.5		
DOMINANT WAVELENGTH	RED		625		nm	
	YELLOW		588			
	GREEN		568			
PEAK EMISSION WAVELENGTH	RED		627		nm	
	YELLOW		590			
	GREEN		565			
VIEWING ANGLE 2θ 1/2	RED		70		Degree	
	YELLOW		70			
	GREEN		70			
CAPACITANCE	RED		15		pF	V _F = 0 V, f = 1 MHz
	YELLOW		20			
	GREEN		15			

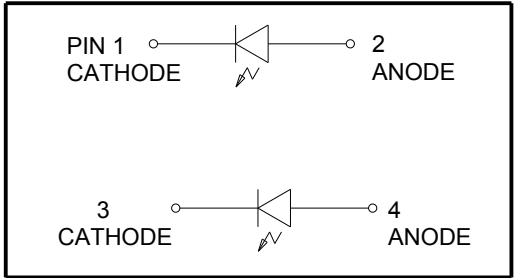


ABSOLUTE MAXIMUM RATING AT 25°C AMBIENT				
POWER DISSIPATION	105	75	62.5	mW
FORWARD CURRENT	30	30	25	mA
DERATING LINEAR FROM 25° C	.40		.33	mA/° C
REVERSE VOLTAGE	5			V
LEAD SOLDERING TEMPERATURE, 3 SEC., 1/16" FROM BODY	260			°C
OPERATING TEMPERATURE	-40 TO +85			°C
STORAGE TEMPERATURE	-40 TO +85			°C

NOTES:

- LED LEAD DIMENSIONS ARE MEASURED AT HOUSING EXIT.
- PIN NUMBERS FOR REFERENCE ONLY, DESIGNATION NON-EXISTENT ON PARTS
- DIALIGHT PART NUMBERS: 571-01XXF
- THIS ASSEMBLY CONTAINS ELECTROSTATIC DISCHARGE SENSITIVE DEVICES (ESDS). MAINTAIN ALL PRECAUTIONARY MEASURES DURING ASSEMBLY, HANDLING AND STORAGE IN ACCORDANCE WITH 1PC-A-610.
- RECOMMENDED WAVE SOLDERING TEMPERATURE: 245° C-255° C FOR 3 SEC (5 SEC MAX)
- DO NOT APPLY STRESS TO THE EPOXY RESIN WHEN TEMPERATURE IS ABOVE 85° C.
- SOLDERING PROFILE APPLIES TO LEAD FREE SOLDERING PROCESS (Sn/Cu/Ag ALLOY).
- DURING WAVE SOLDERING, THE PCB TOP SURFACE SHOULD BE KEPT BELOW 105° C.
- DO NOT SOLDER MORE THAN ONCE.

LED SCHEMATIC



ATTENTION:
OBSERVE PRECAUTIONS FOR
HANDLING ELECTROSTATIC
SENSITIVE DEVICES

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SCALE: DRAWING SCALE ALL DIM'S IN: INCHES (MM)	DRAWING NUMBER C-17454	REV D
TOLERANCES: UNLESS OTHERWISE SPECIFIED FRACTIONS: ± 1/64 DECIMALS (.XX): ± .01 DECIMALS (.XXX): ± .005 DECIMALS (.XXXX): ± .0005 ANGLES: ± 1°	TITLE 2mm LED BI-LEVEL CBI RoHS COMPLIANT	MATERIAL
FINISH	Dialight 1501 ROUTE 34 SOUTH FARMINGDALE, NJ 07727 (732) 919-3119 www.dialight.com	
FSCM 83330	SHEET 1 OF 1	FAMILY TABLE: